Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	**Distribute**		
Sectionals *	**Material Info**	**Subsectionals ***	**A-D**
	Manufacturing Info	***: Required Field**	

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2016-08-08**
Contact Name *	Refer to " Supplier Comment" section	**Contact Title**	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	**Contact Email ***	Refer to " Supplier Comment" section
Authorized Representative *	**Giovanni Giacopello**	**Representative Title**	**ADG Materials Declaration Champion**
Representative Phone *	Refer to " Supplier Comment" section	**Representative Email ***	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	**true**	**Legal Declaration ***	**Standard**

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by giovanni giacopello
Date: 2016.08.08 11:05:48 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
	H2RH*TWU101G	A	ZA41	2016-08-08
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	400.000	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
NAC	NAC	NAC		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
NAC	6.4X10.17X3.24	NA	NAC	
Comment	Package: DO 15; MDF valid for P6KE200A ; P6KE200ARL ; STRVS241X02E			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	H2RH*TWU101G					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Silicon Die	Other inorganic materials	1.821	mg	supplier	Silicon Die	silicon	7440-21-3		1.789	mg	982427	4473
Silicon Die				supplier	Back side metallization	Aluminium (Al)	7429-90-5		0.01	mg	5491	25
Silicon Die				supplier	Back side metallization	Gold (Au)	7440-57-5		0.004	mg	2197	10
Silicon Die				supplier	Back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	9885	45
Lead-frame	Copper & its alloys	281.994	mg	supplier	Alloy	Copper (Cu)	7440-50-8		281.853	mg	999500	704633
Lead-frame				supplier	Alloy	Zinc (Zn)	7440-66-6		0.028	mg	99	70
Lead-frame				supplier	Alloy	Iron (Fe)	7439-89-6		0.028	mg	99	70
Lead-frame				supplier	Alloy	Iron Phosphide(FeP)	26508-33-8		0.085	mg	301	213
Die Attach	Other Organic Materials	4.8	mg	supplier	solder	Silver (Ag)	7440-22-4		0.24	mg	50000	600
Die Attach				supplier	solder	Tin (Sn)	7440-31-5		0.12	mg	25000	300
Die Attach				JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.44	mg	925000	11100
Encapsulation	Other Organic Materials	107.385	mg	supplier	Molding Compound	Silica fused	7631-86-9		42.935	mg	399823	107338
Encapsulation				supplier	Molding Compound	silica quartz	14808-60-7		61.765	mg	575173	154413
Encapsulation				supplier	Molding Compound	phenolic resin	9003-35-4		2.148	mg	20003	5370
Encapsulation				supplier	Molding Compound	carbon black	1333-86-4		0.537	mg	5001	1343
Finishing	Other inorganic materials	4	mg	supplier	connection coating	Tin (Sn)	7440-31-5		4	mg	1000000	10000